

2000P342686

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of

Takahashi, Y. et al.

Serial No.: Not Yet Assigned

Group Art Unit: Not Yet Assigned

Filing Date: Concurrently Herewith

Examiner: Unknown

For: SAW FILTER DEVICE AND PACKAGE FOR ACCOMMODATING THE SAME

Assistant Commissioner of Patents
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Sir:

Prior to examination on the merits and calculation of the filing fee, please amend the above-identified application as follows:

IN THE CLAIMS:

Please amend the claims as follows:

4. (Amended) The SAW filter device, according to claim 1, which further comprises a film of a conductive material covering the front surface of the chip substrate and the interdigital transducers.

11. (Amended) An SAW filter device including an SAW filter according to claim 1, which comprises a plastic package including a terminal member made of metal extending out of the package and extending into the package such as to form an L-shaped portion, the chip substrate being accommodated in the plastic package such that the back surface of the chip substrate is in contact with the L-shaped portion.

Please add claims 13-20 as follows:

--13. (Amended) An SAW filter device including an SAW filter according to claim 2, which comprises a plastic package including a terminal member made of metal extending out of the package and extending into the package such as to form an L-shaped portion, the chip substrate being accommodated in the plastic package such that the back surface of the chip substrate is in contact with the L-shaped portion.

14. (Amended) An SAW filter device including an SAW filter according to claim 3, which comprises a plastic package including a terminal member made of metal extending out of the package and extending into the package such as to form an L-shaped portion, the chip substrate being accommodated in the plastic package such that the back surface of the chip substrate is in contact with the L-shaped portion.

15. (Amended) An SAW filter device including an SAW filter according to claim 4, which comprises a plastic package including a terminal member made of metal extending out of the package and extending into the package such as to form an L-shaped portion, the chip substrate being accommodated in the plastic package such that the back surface of the chip substrate is in contact with the L-shaped portion.

16. (Amended) An SAW filter device including an SAW filter according to claim 5, which comprises a plastic package including a terminal member made of metal extending out of the package and extending into the package such as to form an L-shaped portion, the chip

substrate being accommodated in the plastic package such that the back surface of the chip substrate is in contact with the L-shaped portion.

17. (Amended) An SAW filter device including an SAW filter according to claim 6, which comprises a plastic package including a terminal member made of metal extending out of the package and extending into the package such as to form an L-shaped portion, the chip substrate being accommodated in the plastic package such that the back surface of the chip substrate is in contact with the L-shaped portion.

18. (Amended) An SAW filter device including an SAW filter according to claim 7, which comprises a plastic package including a terminal member made of metal extending out of the package and extending into the package such as to form an L-shaped portion, the chip substrate being accommodated in the plastic package such that the back surface of the chip substrate is in contact with the L-shaped portion.

19. (Amended) An SAW filter device including an SAW filter according to claim 8, which comprises a plastic package including a terminal member made of metal extending out of the package and extending into the package such as to form an L-shaped portion, the chip substrate being accommodated in the plastic package such that the back surface of the chip substrate is in contact with the L-shaped portion.

20. (Amended) An SAW filter device including an SAW filter according to claim 9, which comprises a plastic package including a terminal member made of metal extending out of the

2000P342686

package and extending into the package such as to form an L-shaped portion, the chip substrate being accommodated in the plastic package such that the back surface of the chip substrate is in contact with the L-shaped portion. --

2000P342686

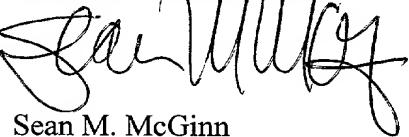
REMARKS

Claim 4 has been amended to be dependent on claim 1, and claim 11 has been amended to delete multiple-dependency and claims 13-20 have been added accordingly.

Attached hereto is a marked-up version of the changes made to the **claims** by the current amendment. The attached pages are captioned "**Version with markings to show changes made.**"

Early, favorable prosecution on the merits is respectfully requested.

Please charge any deficiencies in fees and credit any overpayment of fees to Attorney's Deposit Account No. 50-0481.

Respectfully submitted,

Sean M. McGinn
Registration No.: 34,386

Date: November 7, 2001
McGinn & Gibb, PLLC
8321 Old Courthouse Road; Suite 200
Vienna, Virginia 22182-3817
(703) 761-4100
Customer No. 21254

VERSION WITH MARKINGS TO SHOW CHANGES MADE

In the claims:

4. (Amended) The SAW filter device, according to claim 1, which further comprises a film of a conductive material covering the front surface of the chip substrate and the interdigital transducers.

11. (Amended) An SAW filter device including an SAW filter according to [one of claims 1 to 9] claim 1, which comprises a plastic package including a terminal member made of metal extending out of the package and extending into the package such as to form an L-shaped portion, the chip substrate being accommodated in the plastic package such that the back surface of the chip substrate is in contact with the L-shaped portion.